



Click here for the 3D model.

General Information	
Series	KONNEKT Auto COG
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra- Stable, Class I
Features	High Density Packaging
RoHS	Yes
Termination	Tin
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	151.24 mg
Chip Size	1210-2
Shelf Life	78 Weeks
MSL	1

Dimensions	
L	3.2mm +/-0.2mm
W	2.5mm +/-0.2mm
т	3.4mm +/-0.4mm
В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	450

Specifications	
Capacitance	0.2 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 PPM/C
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	5 GOhms

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